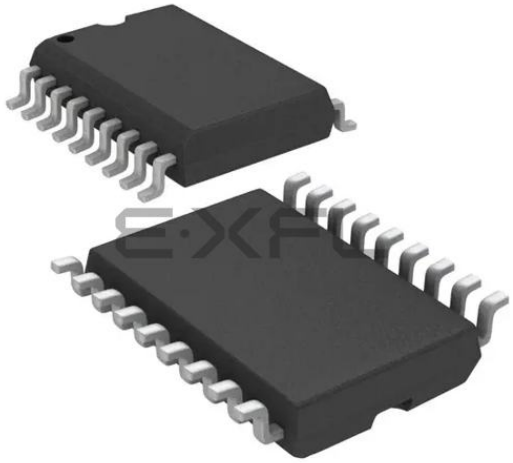

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Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c558t-04i-so

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4.0 MEMORY ORGANIZATION

4.1 Program Memory Organization

The PIC16C55X has a 13-bit program counter capable of addressing an 8 K x 14 program memory space. Only the first 512 x 14 (0000h - 01FFh) for the PIC16C554 and 2K x 14 (0000h - 07FFh) for the PIC16C557 and PIC16C558 are physically implemented. Accessing a location above these boundaries will cause a wrap-around within the first 512 x 14 spaces in the PIC16C554, or 2K x 14 space of the PIC16C558 and PIC16C557. The RESET vector is at 0000h and the interrupt vector is at 0004h (Figure 4-1, Figure 4-2).

FIGURE 4-1: PROGRAM MEMORY MAP AND STACK FOR THE PIC16C554

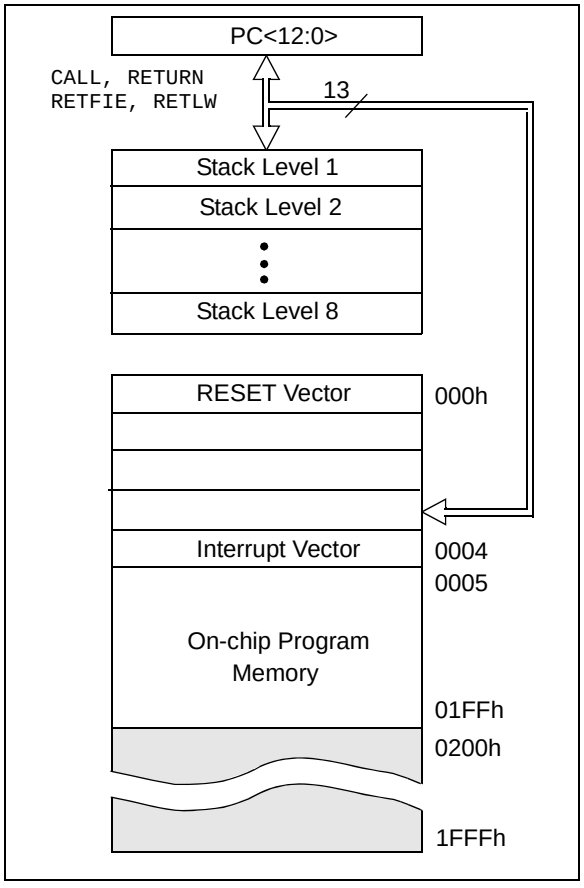
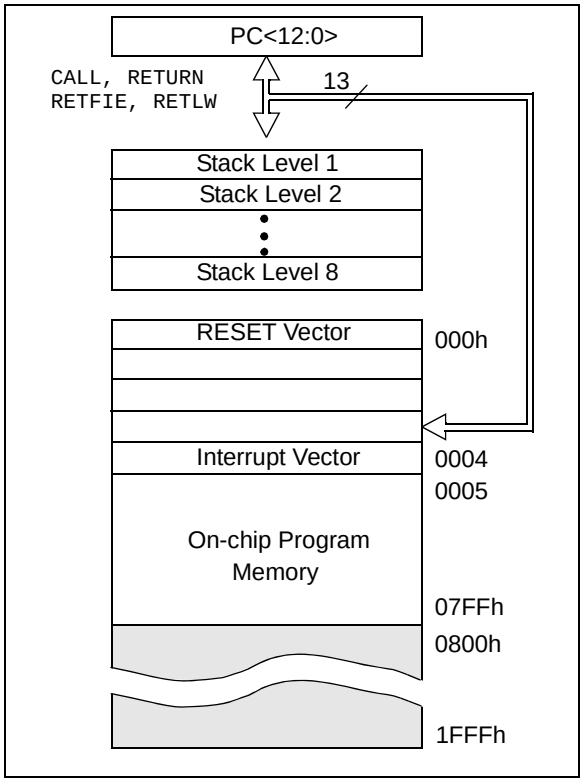


FIGURE 4-2: PROGRAM MEMORY MAP AND STACK FOR THE PIC16C557 AND PIC16C558



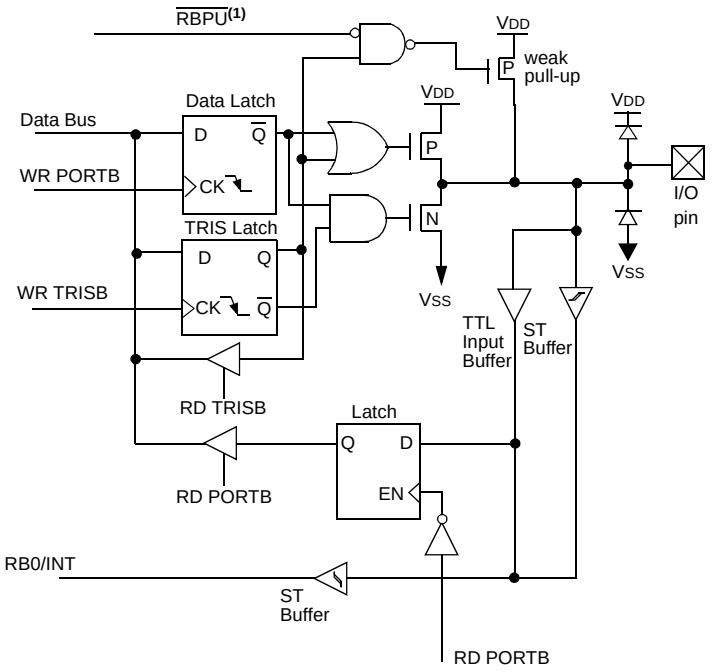
4.2 Data Memory Organization

The data memory (Figure 4-3 through Figure 4-5) is partitioned into two banks which contain the General Purpose Registers (GPR) and the Special Function Registers (SFR). Bank 0 is selected when the RP0 bit (STATUS <5>) is cleared. Bank 1 is selected when the RP0 bit is set. The Special Function Registers are located in the first 32 locations of each Bank. Register locations 20-6Fh (Bank 0) on the PIC16C554 and 20-7Fh (Bank 0) and A0-BFh (Bank 1) on the PIC16C558 and PIC16C557 are General Purpose Registers implemented as static RAM. Some special purpose registers are mapped in Bank 1.

4.2.1 GENERAL PURPOSE REGISTER FILE

The register file is organized as 80 x 8 in the PIC16C554 and 128 x 8 in the PIC16C557 and PIC16C558. Each can be accessed either directly or indirectly through the File Select Register, FSR (Section 4.4).

FIGURE 5-4: BLOCK DIAGRAM OF RB3:RB0 PINS



Note 1: TRISB = 1 enables weak pull-up if $\overline{RBPU}$ = '0' (OPTION<7>).

TABLE 5-3: PORTB FUNCTIONS

Name	Bit #	Buffer Type	Function
RB0/INT	Bit 0	TTL/ST(1)	Bi-directional I/O port. Internal software programmable weak pull-up.
RB1	Bit 1	TTL	Bi-directional I/O port. Internal software programmable weak pull-up.
RB2	Bit 2	TTL	Bi-directional I/O port. Internal software programmable weak pull-up.
RB3	Bit 3	TTL	Bi-directional I/O port. Internal software programmable weak pull-up.
RB4	Bit 4	TTL	Bi-directional I/O port (with interrupt-on-change). Internal software programmable weak pull-up.
RB5	Bit 5	TTL	Bi-directional I/O port (with interrupt-on-change). Internal software programmable weak pull-up.
RB6	Bit 6	TTL/ST(2)	Bi-directional I/O port (with interrupt-on-change). Internal software programmable weak pull-up. Serial programming clock pin.
RB7	Bit 7	TTL/ST(2)	Bi-directional I/O port (with interrupt-on-change). Internal software programmable weak pull-up. Serial programming data pin.

Legend: ST = Schmitt Trigger, TTL = TTL input
Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.
2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.

TABLE 5-4: SUMMARY OF REGISTERS ASSOCIATED WITH PORTB AND TRISB

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other RESETS
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xxxx	uuuu uuuu
86h	TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	1111 1111	1111 1111
81h	OPTION	$\overline{RBPU}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
0BH, 8BH	INTCON	GIE	Reserved	T0IE	INTE	BRIE	T0IF	INTF	RBIF	0000 000x	0000 000x

Legend: x = unknown, u = unchanged
Note 1: Shaded bits are not used by PORTB.

5.3 PORTC and TRISC Registers(1)

PORTC is a 8-bit wide latch. All pins have data direction bits (TRIS registers) which can configure these pins as input or output.

A '1' in the TRISC register puts the corresponding output driver in a Hi-impedance mode. A '0' in the TRISC register puts the contents of the output latch on the selected pin(s).

Reading the PORTC register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. So a write to a port implies that the port pins are first read, then this value is modified and written to the port data latch

FIGURE 5-5: BLOCK DIAGRAM OF PORT PINS RC<7:0>

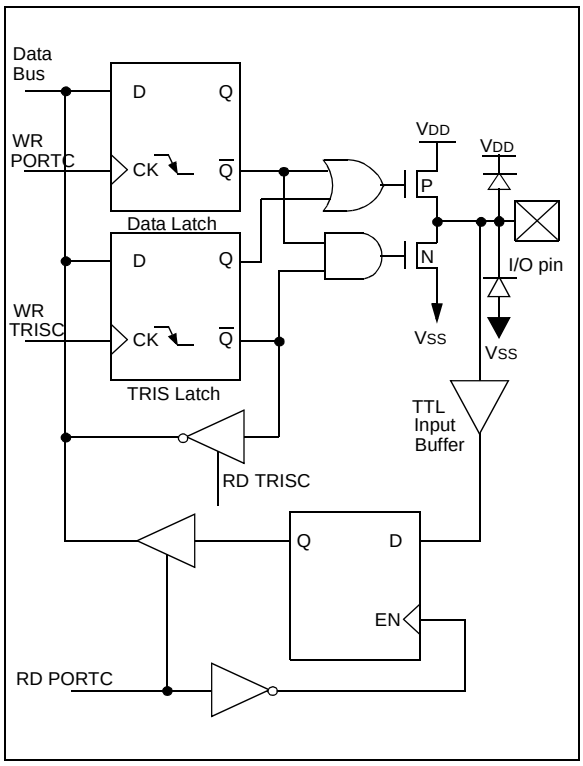


TABLE 5-5: PORTC FUNCTIONS

Name	Bit #	Buffer Type	Function
RC0	Bit 0	TTL	Bi-directional I/O port.
RC1	Bit 1	TTL	Bi-directional I/O port.
RC2	Bit 2	TTL	Bi-directional I/O port.
RC3	Bit 3	TTL	Bi-directional I/O port.
RC4	Bit 4	TTL	Bi-directional I/O port.
RC5	Bit 5	TTL	Bi-directional I/O port.
RC6	Bit 6	TTL	Bi-directional I/O port.
RC7	Bit 7	TTL	Bi-directional I/O port.

Legend: ST = Schmitt Trigger, TTL = TTL input

TABLE 5-6: SUMMARY OF REGISTERS ASSOCIATED WITH PORTC AND TRISC

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other RESETS
07h	PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx xxxx	uuuu uuuu
87h	TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	1111 1111	1111 1111

Legend: x = unknown, u = unchanged
Note 1: PIC16C557 ONLY.

5.4 I/O Programming Considerations

5.4.1 BI-DIRECTIONAL I/O PORTS

Any instruction which writes, operates internally as a read followed by a write operation. The BCF and BSF instructions, for example, read the register into the CPU, execute the bit operation and write the result back to the register. Caution must be used when these instructions are applied to a port with both inputs and outputs defined. For example, a BSF operation on bit5 of PORTB will cause all eight bits of PORTB to be read into the CPU. Then the BSF operation takes place on bit5 and PORTB is written to the output latches. If another bit of PORTB is used as a bi-directional I/O pin (e.g., bit 0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and re-written to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the Input mode, no problem occurs. However, if bit 0 is switched into Output mode later on, the content of the data latch may now be unknown.

Reading the port register, reads the values of the port pins. Writing to the port register writes the value to the port latch. When using read-modify-write instructions (ex. BCF, BSF, etc.) on a port, the value of the port pins is read, the desired operation is done to this value, and this value is then written to the port latch.

Example 5-1 shows the effect of two sequential read-modify-write instructions (ex., BCF, BSF, etc.) on an I/O port.

A pin actively outputting a low or high should not be driven from external devices at the same time in order to change the level on this pin (“wired-or”, “wired-and”). The resulting high output currents may damage the chip.

6.5.1 RB0/INT INTERRUPT

An external interrupt on RB0/INT pin is edge triggered: either rising if INTEDG bit (OPTION<6>) is set, or falling if INTEDG bit is clear. When a valid edge appears on the RB0/INT pin, the INTF bit (INTCON<1>) is set. This interrupt can be disabled by clearing the INTE control bit (INTCON<4>). The INTF bit must be cleared in software in the interrupt service routine before re-enabling this interrupt. The RB0/INT interrupt can wake-up the processor from SLEEP, if the INTE bit was set prior to going into SLEEP. The status of the GIE bit decides whether or not the processor branches to the interrupt vector following wake-up. See Section 6.8 for details on SLEEP and Figure 6-14 for timing of wake-up from SLEEP through RB0/INT interrupt.

6.5.2 TMR0 INTERRUPT

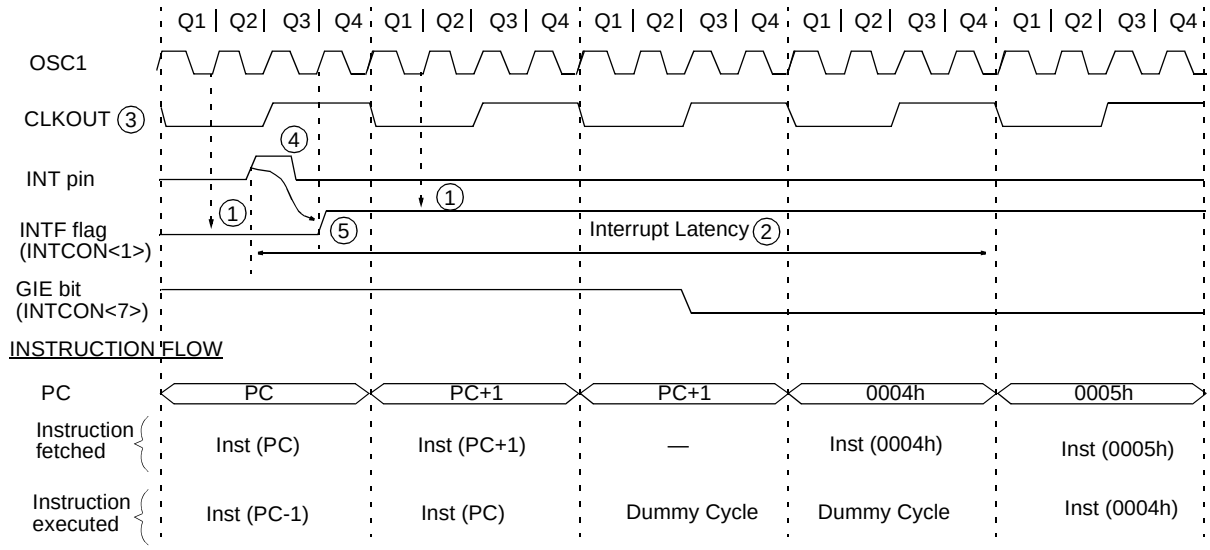
An overflow (FFh $\rightarrow$ 00h) in the TMR0 register will set the T0IF (INTCON<2>) bit. The interrupt can be enabled/disabled by setting/clearing T0IE (INTCON<5>) bit. For operation of the Timer0 module, see Section 7.0.

6.5.3 PORTB INTERRUPT

An input change on PORTB <7:4> sets the RBIF (INTCON<0>) bit. The interrupt can be enabled/disabled by setting/clearing the RBIE (INTCON<4>) bit. For operation of PORTB (Section 5.2).

Note:	If a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the RBIF interrupt flag may get set.

FIGURE 6-12: INT PIN INTERRUPT TIMING



Note 1: INTF flag is sampled here (every Q1).

2: Interrupt latency = 3-4 TCY where TCY = instruction cycle time. Latency is the same whether Inst (PC) is a single cycle or a 2-cycle instruction.

3: CLKOUT is available only in RC Oscillator mode.

4: For minimum width of INT pulse, refer to AC specs.

5: INTF is enabled to be set anytime during the Q4-Q1 cycles.

FIGURE 7-3: TIMER0 TIMING: INTERNAL CLOCK/PRESCALE 1:2

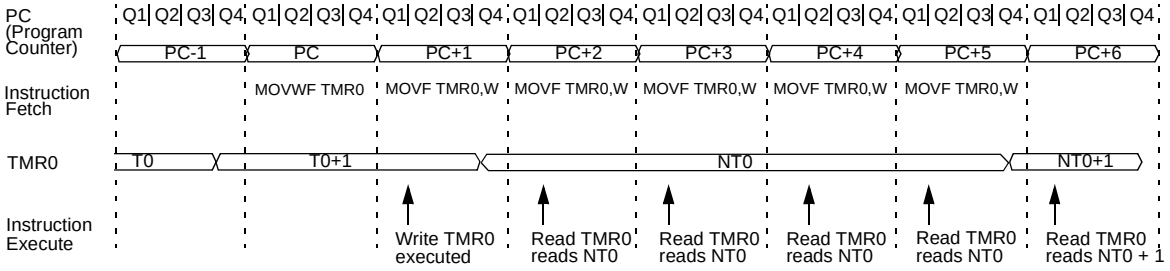
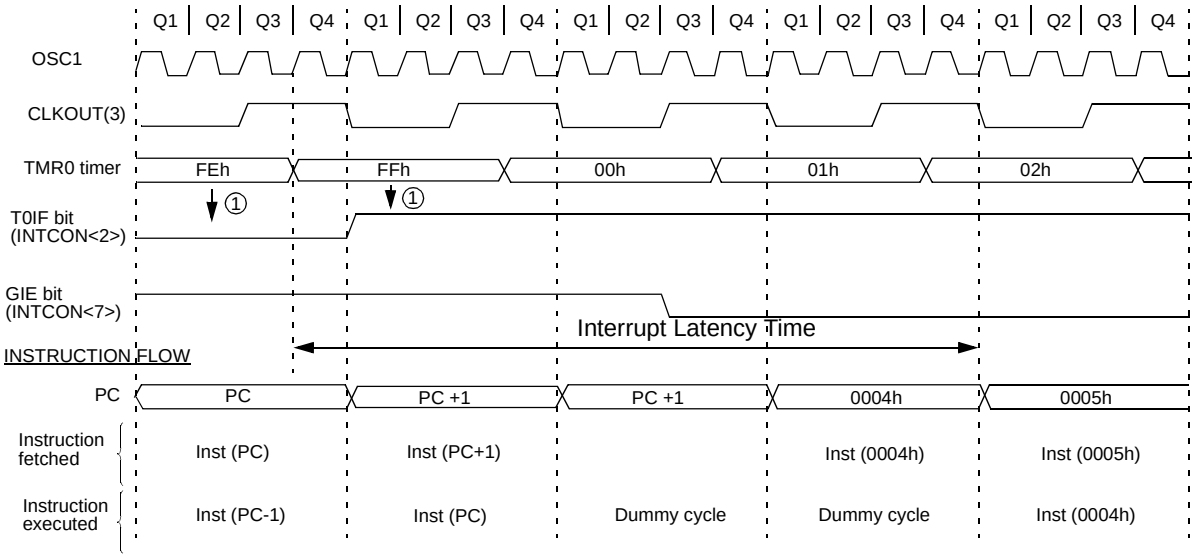


FIGURE 7-4: TIMER0 INTERRUPT TIMING



Note 1: T0IF interrupt flag is sampled here (every Q1).
2: Interrupt latency = 4 TCY, where TCY = instruction cycle time.
3: CLKOUT is available only in RC Oscillator mode.

SUBWF **Subtract W from f**

Syntax: [*label*] SUBWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) - (W) → (dest)

Status Affected: C, DC, Z

Encoding:

00	0010	dfff	ffff

Description: Subtract (2's complement method) W register from register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example 1:
```
SUBWF   REG1,1
```
Before Instruction
REG1 = 3
W = 2
C = ?
After Instruction
REG1 = 1
W = 2
C = 1; result is positive

Example 2: Before Instruction
REG1 = 2
W = 2
C = ?
After Instruction
REG1 = 0
W = 2
C = 1; result is zero

Example 3: Before Instruction
REG1 = 1
W = 2
C = ?
After Instruction
REG1 = 0xFF
W = 2
C = 0; result is negative

SWAPF **Swap Nibbles in f**

Syntax: [*label*] SWAPF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f<3:0>) → (dest<7:4>),
(f<7:4>) → (dest<3:0>)

Status Affected: None

Encoding:

00	1110	dfff	ffff

Description: The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0 the result is placed in W register. If 'd' is 1 the result is placed in register 'f'.

Words: 1

Cycles: 1

Example
```
SWAPF   REG,    0
```
Before Instruction
REG1 = 0xA5
After Instruction
REG1 = 0xA5
W = 0x5A

TRIS **Load TRIS Register**

Syntax: [*label*] TRIS f

Operands: $5 \le f \le 7$

Operation: (W) → TRIS register f;

Status Affected: None

Encoding:

00	0000	0110	0fff

Description: The instruction is supported for code compatibility with the PIC16C5X products. Since TRIS registers are readable and writable, the user can directly address them.

Words: 1

Cycles: 1

Example

To maintain upward compatibility with future PIC MCU products, do not use this instruction.

XORLW **Exclusive OR Literal with W**

Syntax: [*label*] XORLW k

Operands: $0 \le k \le 255$

Operation: (W) .XOR. k → (W)

Status Affected: Z

Encoding:

11	1010	kkkk	kkkk

Description: The contents of the W register are XOR'ed with the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Example:

```
XORLW   0xAF
```

Before Instruction

W = 0xB5

After Instruction

W = 0x1A

XORWF **Exclusive OR W with f**

Syntax: [*label*] XORWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (W) .XOR. (f) → (dest)

Status Affected: Z

Encoding:

00	0110	dfff	ffff

Description: Exclusive OR the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example

```
XORWF   REG     1
```

Before Instruction

REG = 0xAF
W = 0xB5

After Instruction

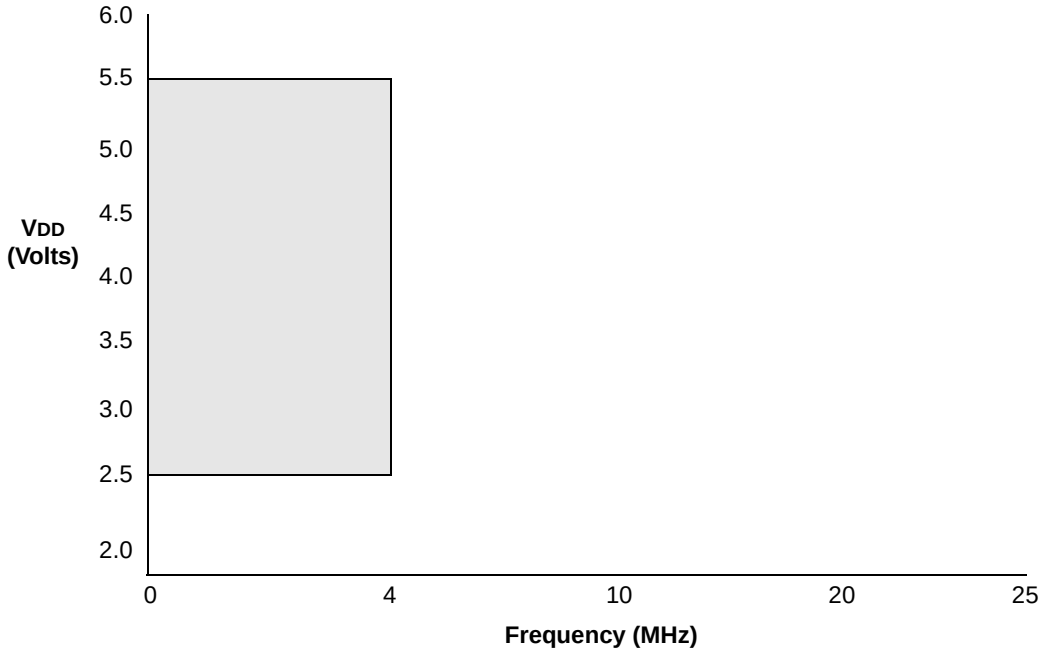
REG = 0x1A
W = 0xB5

TABLE 9-1: DEVELOPMENT TOOLS FROM MICROCHIP

Category	Tool	PIC12CXXX	PIC14000	PIC16C5X	PIC16C6X	PIC16CXXX	PIC16F62X	PIC16C7X	PIC16C7XX	PIC16C8X	PIC16F8XX	PIC16C9XX	PIC17C4X	PIC17C7XX	PIC18CXX2	PIC18FXXX	24CXX/ 25CXX/ 93CXX	HCSXXX	MCRFXXX	MCP2510
Software Tools	MPLAB® Integrated Development Environment	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓				
	MPLAB® C17 C Compiler												✓	✓						
	MPLAB® C18 C Compiler														✓	✓				
	MPASM™ Assembler/ MPLINK™ Object Linker	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
Emulators	MPLAB® ICE In-Circuit Emulator	✓	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓	✓				
	ICEPIC™ In-Circuit Emulator	✓		✓	✓	✓		✓	✓	✓		✓								
Debugger	MPLAB® ICD In-Circuit Debugger				✓*			✓*			✓					✓				
Programmers	PICSTART® Plus Entry Level Development Programmer	✓	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓	✓				
	PRO MATE® II Universal Device Programmer	✓	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
Demo Boards and Eval Kits	PICDEM™ 1 Demonstration Board			✓		✓		✓†		✓			✓							
	PICDEM™ 2 Demonstration Board				✓†			✓†							✓	✓				
	PICDEM™ 3 Demonstration Board											✓								
	PICDEM™ 14A Demonstration Board		✓																	
	PICDEM™ 17 Demonstration Board													✓						
	KEELOQ® Evaluation Kit																	✓		
	KEELOQ® Transponder Kit																	✓		
	microID™ Programmer's Kit																		✓	
	125 kHz microID™ Developer's Kit																		✓	
	125 kHz Anticollision microID™ Developer's Kit																		✓	
	13.56 MHz Anticollision microID™ Developer's Kit																		✓	
	MCP2510 CAN Developer's Kit																			✓

* Contact the Microchip Technology Inc. web site at www.microchip.com for information on how to use the MPLAB® ICD In-Circuit Debugger (DV164001) with PIC16C62, 63, 64, 65, 72, 73, 74, 76, 77.
** Contact Microchip Technology Inc. for availability date.
†

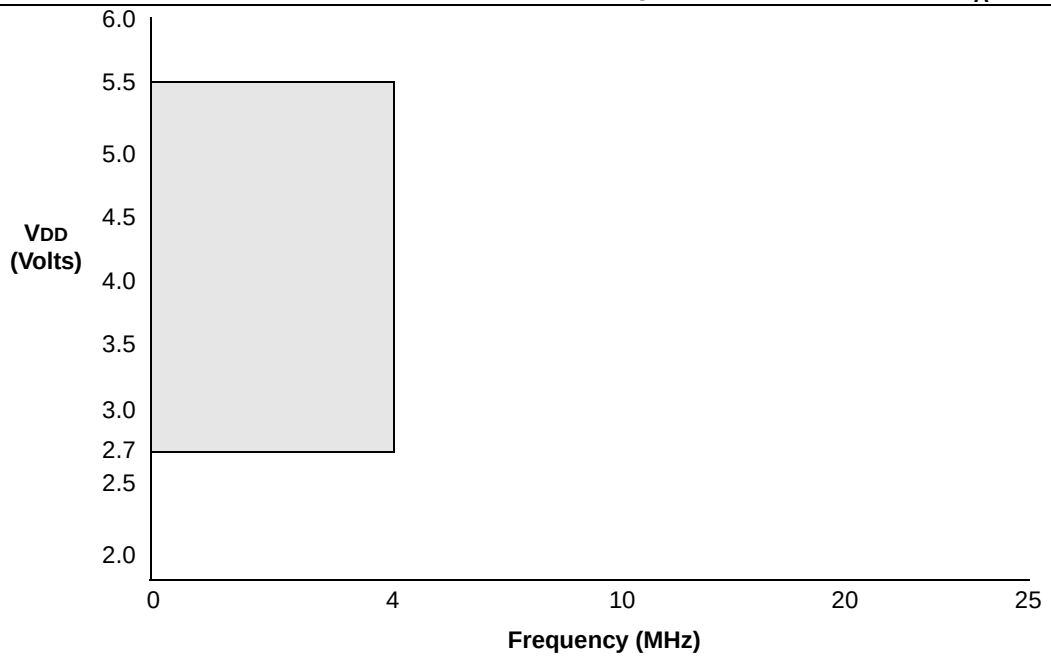
FIGURE 10-3: VOLTAGE-FREQUENCY GRAPH, 0°C ≤ T_A ≤ +85°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

FIGURE 10-4: PIC16LC554/557/558 VOLTAGE-FREQUENCY GRAPH, -40°C ≤ T_A ≤ 0°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

10.1 DC Characteristics: PIC16C55X-04 (Commercial, Industrial, Extended) PIC16C55X-20 (Commercial, Industrial, Extended) HCS1365-04 (Commercial, Industrial, Extended)

DC Characteristics			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D020	IPD	**Power-Down Current(3)**					
		16LC55X	—	0.7	2	µA	VDD = 3.0V, WDT disabled
		16C55X	—	1.0	2.5 15	µA µA	VDD = 4.0V, WDT disabled (+85°C to +125°C)
	ΔIWDT	**WDT Current(5)**					
		16LC55X	—	6.0	15	µA	VDD = 3.0V
		16C55X	—	6.0	20	µA	VDD = 4.0V (+85°C to +125°C)

* These parameters are characterized but not tested.

† Data is "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active Operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins configured as input, pulled to VDD,
MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins configured as input and tied to VDD or VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

10.2 DC Characteristics: PIC16C55X (Commercial, Industrial, Extended) PIC16LC55X(Commercial, Industrial, Extended)

DC Characteristics			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for automotive Operating voltage VDD range as described in DC spec Table 10-1				
Param. No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Unit**	**Conditions**
	VIL	**Input Low Voltage**					
		I/O ports					
D030		with TTL buffer	VSS	—	0.8V 0.15 VDD	V	VDD = 4.5V to 5.5V otherwise
D031		with Schmitt Trigger input	VSS		0.2 VDD	V	
D032		$\overline{MCLR}$, RA4/T0CKI,OSC1 (in RC mode)	VSS	—	0.2 VDD	V	**(Note1)**
D033		OSC1 (in XT* and HS)	VSS	—	0.3 VDD	V	
		OSC1 (in LP*)	VSS	—	0.6 VDD-1.0	V	
	VIH	**Input High Voltage**					
		I/O ports		—			
D040		with TTL buffer	2.0V 0.8 + 0.25 VDD	— —	VDD VDD	V V	VDD = 4.5V to 5.5V otherwise
D041		with Schmitt Trigger input	0.8V		VDD		
D042		$\overline{MCLR}$ RA4/T0CKI	0.8 VDD	—	VDD	V	
D043 D043A		OSC1 (XT*, HS and LP*) OSC1 (in RC mode)	0.7 VDD 0.9 VDD	—	VDD	V	 **(Note1)**
D070	IPURB	PORTB weak pull-up current	50	200	400	µA	VDD = 5.0V, VPIN = VSS
	IIL	**Input Leakage Current(2)(3)**					
		I/O ports (Except PORTA)			±1.0	µA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
D060		PORTA	—	—	±0.5	µA	Vss ≤ VPIN ≤ VDD, pin at hi-impedance
D061		RA4/T0CKI	—	—	±1.0	µA	Vss ≤ VPIN ≤ VDD
D063		OSC1, $\overline{MCLR}$	—	—	±5.0	µA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
	VOL	**Output Low Voltage**					
D080		I/O ports	—	—	0.6	V	IOL=8.5 mA, VDD=4.5V, -40° to +85°C
			—	—	0.6	V	IOL=7.0 mA, VDD=4.5V, +125°C
D083		OSC2/CLKOUT	—	—	0.6	V	IOL=1.6 mA, VDD=4.5V, -40° to +85°C
		(RC only)	—	—	0.6	V	IOL=1.2 mA, VDD=4.5V, +125°C
	VOH	**Output High Voltage(3)**					
D090		I/O ports (Except RA4)	VDD-0.7	—	—	V	IOH=-3.0 mA, VDD=4.5V, -40° to +85°C

* These parameters are characterized but not tested.

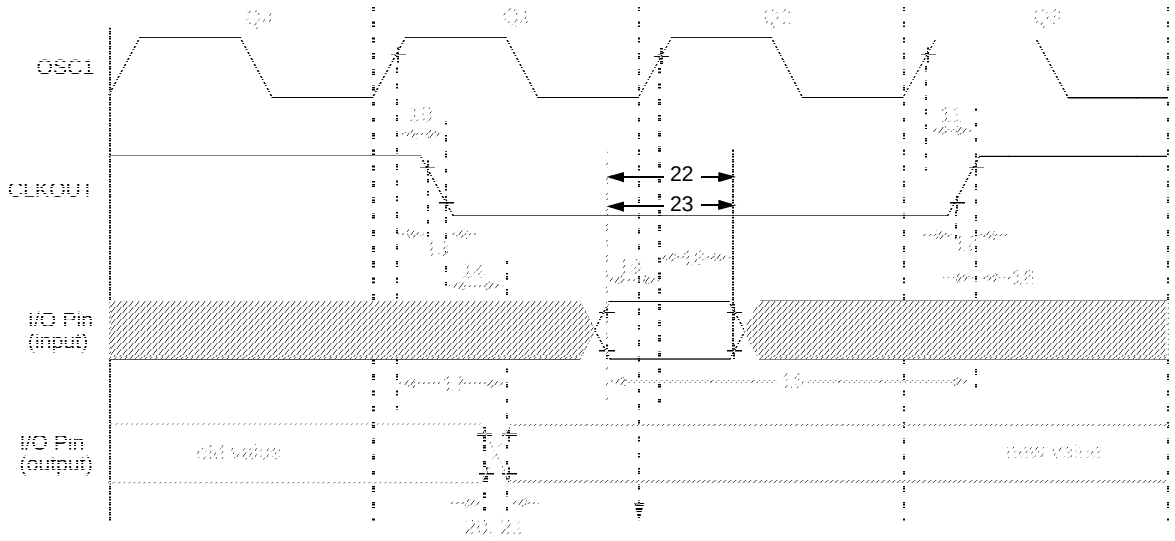
† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16C55X be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

FIGURE 10-7: CLKOUT AND I/O TIMING



Note 1: All tests must be done with specified capacitance loads (Figure 10-5) 50 pF on I/O pins and CLKOUT.

FIGURE 10-9: TIMER0 CLOCK TIMING

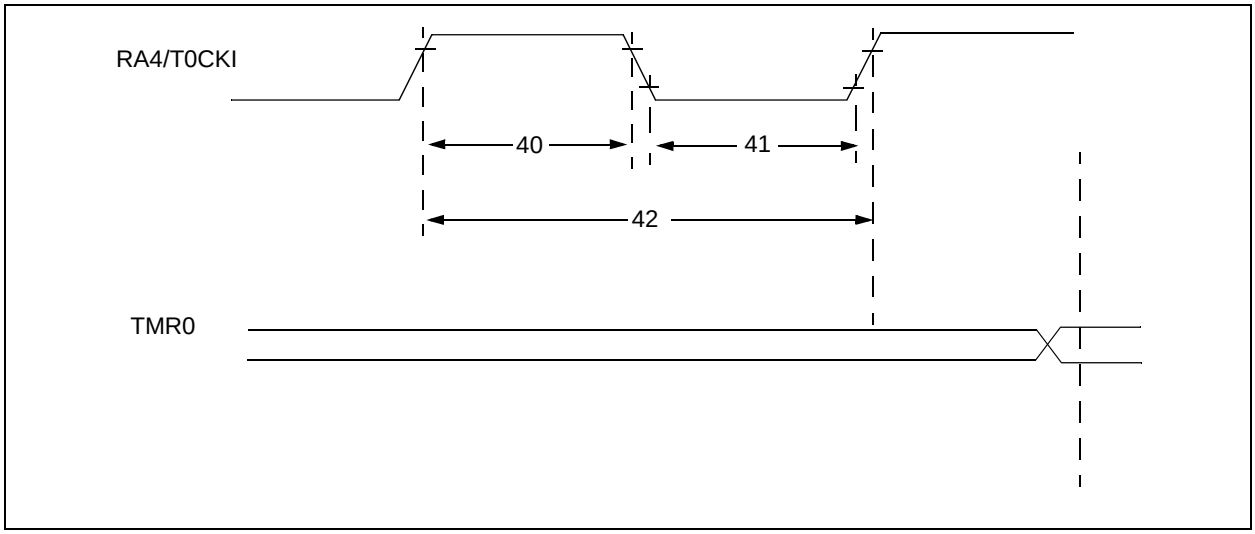


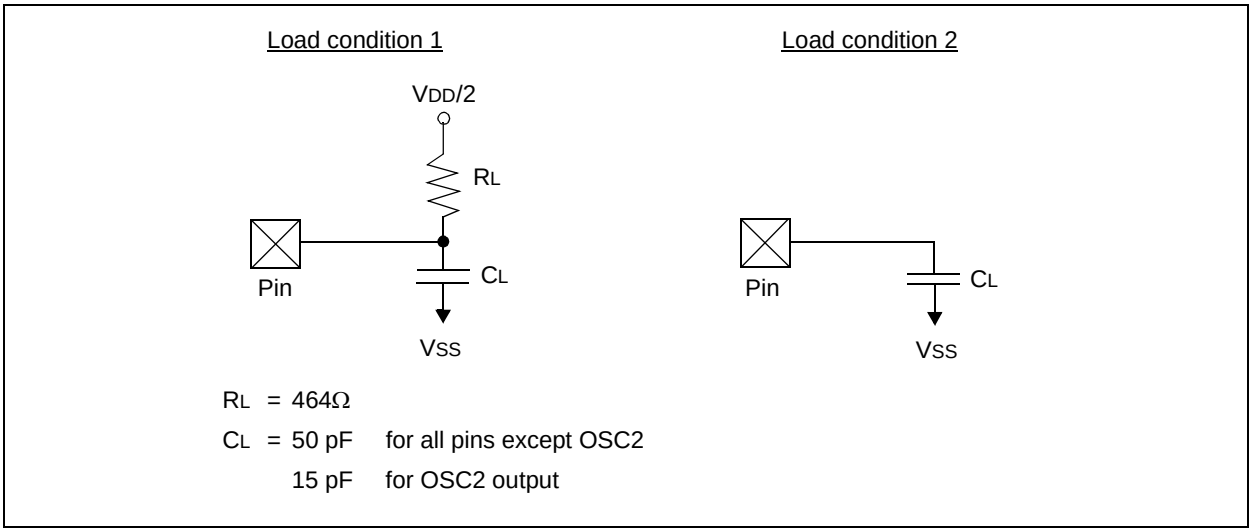
TABLE 10-4: TIMER0 CLOCK REQUIREMENTS

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width	No Prescaler	0.5 TCY + 20*	—	—	ns	
			With Prescaler	10*	—	—	ns	
41	Tt0L	T0CKI Low Pulse Width	No Prescaler	0.5 TCY + 20*	—	—	ns	
			With Prescaler	10*	—	—	ns	
42	Tt0P	T0CKI Period		$\frac{T_{CY} + 40}{N}$*	—	—	ns	N = prescale value (1, 2, 4, ..., 256)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

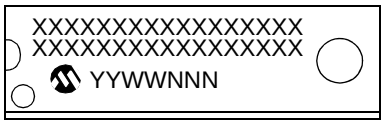
FIGURE 10-10: LOAD CONDITIONS



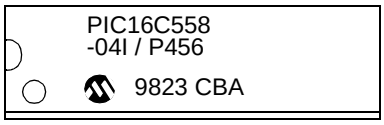
11.0 PACKAGING INFORMATION

11.1 Package Marking Information

18-Lead PDIP

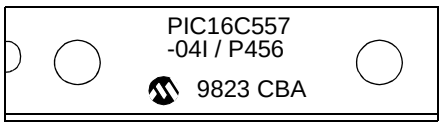


Example

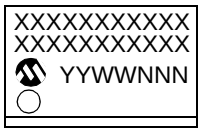


28-Lead PDIP

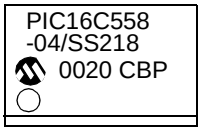
Example



20-Lead SSOP



Example



28-Lead SSOP

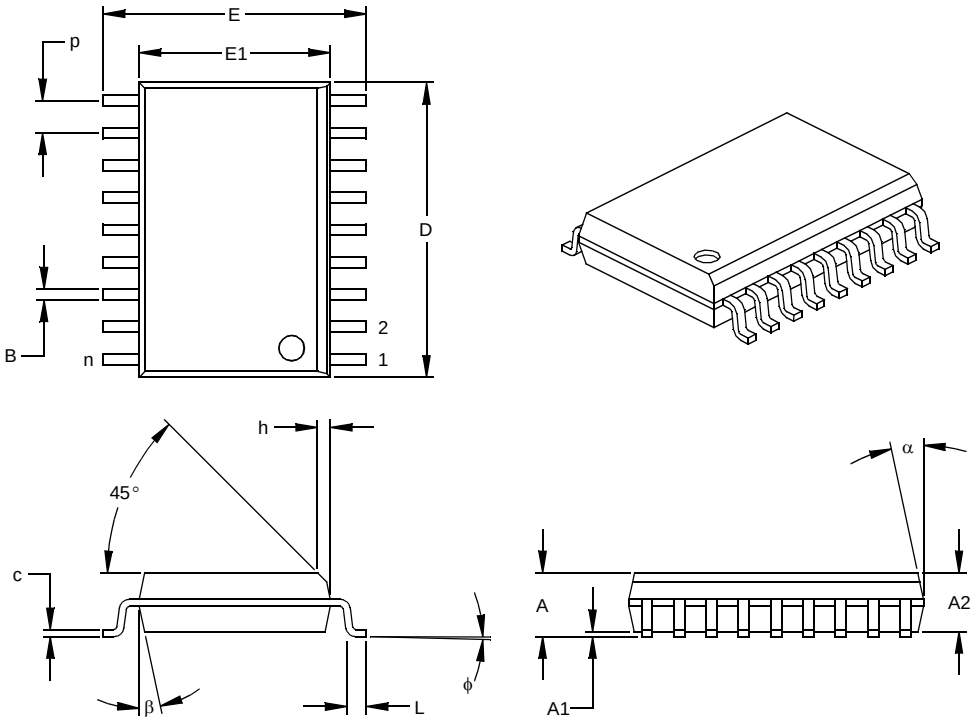
Example

Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

18-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	ϕ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.012	0.23	0.27	0.30
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-013
Drawing No. C04-051

INDEX

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	X	/XX	XXX
Device	Temperature Range	Package	Pattern

Device	PIC17C756: Standard V_{DD} range PIC17C756T: (Tape and Reel) PIC17LC756: Extended V_{DD} range	
Temperature Range	- = 0°C to +70°C I = -40°C to +85°C	
Package	CL = Windowed LCC PT = TQFP L = PLCC	
Pattern	QTP, SQTP, ROM Code (factory specified) or Special Requirements. Blank for OTP and Windowed devices.	

Examples:

a) PIC17C756–16L Commercial Temp., PLCC package, 16 MHz, normal V_{DD} limits

b) PIC17LC756–08/PT Commercial Temp., TQFP package, 8MHz, extended V_{DD} limits

c) PIC17C756–33I/PT Industrial Temp., TQFP package, 33 MHz, normal V_{DD} limits

* JW Devices are UV erasable and can be programmed to any device configuration. JW Devices meet the electrical requirement of each oscillator type.

Sales and Support

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Worldwide Site (www.microchip.com)

